

CHIP-TYPE ELECTRONIC COMPONENT

Patent number: JP2002184604
Publication date: 2002-06-28
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Classification:
- international: H01C7/00; H01G4/12
- european:
Application number: JP20010332229 20011030
Priority number(s): JP20010332229 20011030

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Abstract of JP2002184604

PROBLEM TO BE SOLVED: To realize a method of manufacturing chip-type electronic components having superior electrical characteristics at a low cost by using the terminal electrode structure of various chip-type electronic components in common, and to provide various chip-type electrode components equipped with terminal electrodes having high adhesive force and high solder wettability. **SOLUTION:** Conductive metal powder and curing resin are kneaded together into a conductive resin paste, the conductive resin paste is applied for the formation of a base electrode layer 3 of thickness 10 μ m or larger, and a terminal electrode is composed of the base electrode layer 3 and a solder layer 6, which is 3 μ m or larger in thickness and formed on the prime electrode layer 3 through a complex reaction occurring between organic acid lead and metallic tin.

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